

PRODUCT/PROCESS CHANGE NOTICE (PCN)

Product Affect	ted: All Products in 32 pins and 44 p TSOP Type II packages (PH32 of g Location Affected: All	oins & PH44)	MEANS OF I Product M Back Mar Date Code Other Additional Date Samples:	k e Shipping material
E-mail:	pstow@idt.com			
DESCRIPTION AND PURPOSE OF CHANGE: □ Die Technology □ Wafer Fabrication Process □ Assembly Process □ Equipment □ Equipment □ Material □ Testing □ Manufacturing Site □ Data Sheet □ Data Sheet				
RELIABILITY/QUALIFICATION SUMMARY: N/A				
CUSTOMER ACKNOWLEDGMENT OF RECEIPT: IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.				
Customer:			Approva	al for shipments prior to effective date.
Name/Date:		E-N	Mail Address:	
Title:		Pho	one#/Fax#:	
CUSTOMER COMMENTS:				
RECD. BY:			DATE:	